



# SOT1952-1

PLLMC14, plastic leadless module carrier, 14 terminals, 2.6 mm pitch, 15 mm x 12.8 mm x 0.39 mm body

8 February 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	PLLMC14
<b>Package style descriptive code</b>	PLLMC (plastic leadless module carrier)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-01-2019
<b>Manufacturer package code</b>	98ASA01387D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	15	-	mm
package width	-	12.8	-	mm
package height	-	0.39	-	mm
nominal pitch	-	2.6	-	mm
actual quantity of termination	-	14	-	



2 Package outline

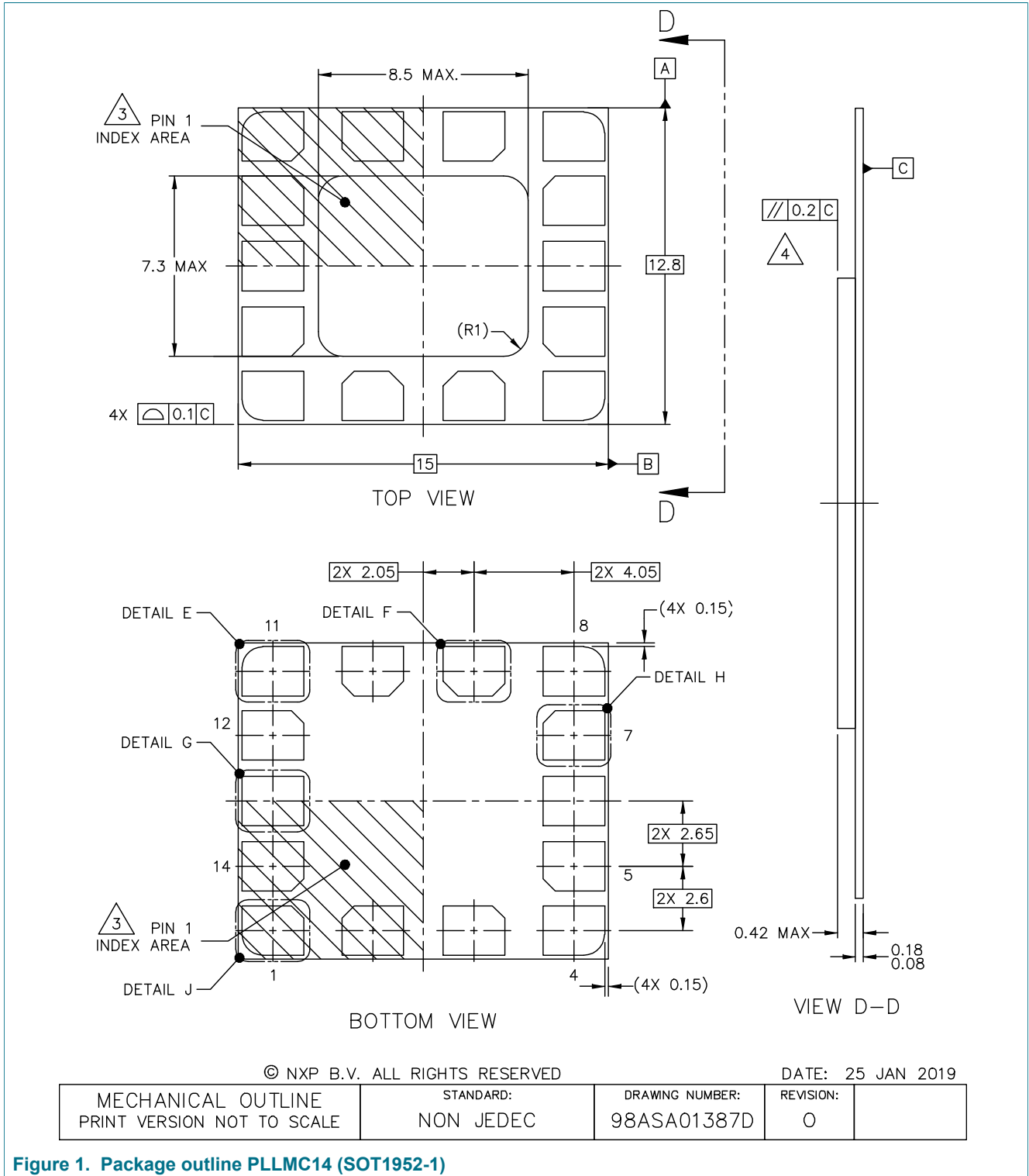
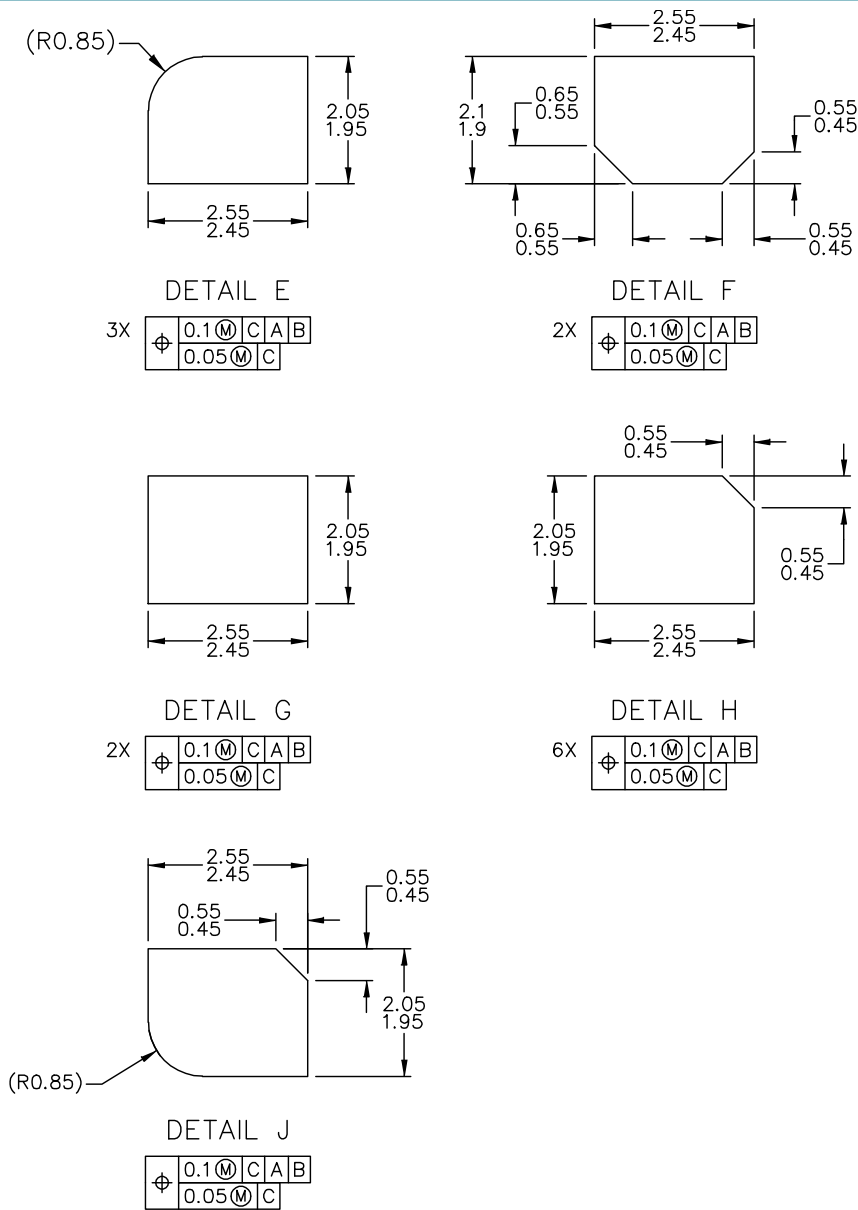


Figure 1. Package outline PLLMC14 (SOT1952-1)



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DATE: 25 JAN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01387D	REVISION: 0	
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Figure 2. Package outline detail PLLMC14 (SOT1952-1)

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 3. Package outline note PLLMC14 (SOT1952-1)

### 3 Legal information

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